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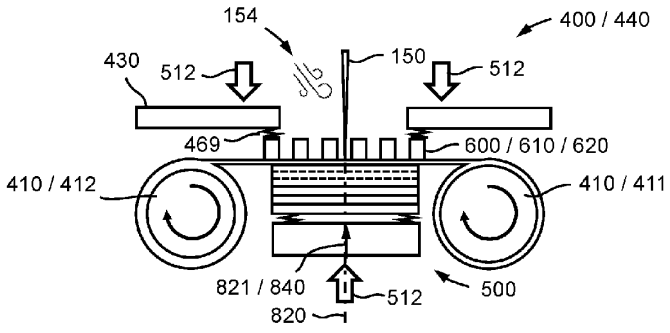


FIG. 6B

(57) Abstract: An apparatus includes a laser, a clamp, and a workpiece positioner. The laser is operable as a pulsed laser to cut a sheet. The clamp is displaceable relative to a working zone of the apparatus. The workpiece positioner is configured to support a workpiece in the working zone with the workpiece. In a bonding stage, the clamp and the workpiece positioner are operable to cooperatively push the sheet and the workpiece toward one another, and a selective bonding of the sheet with the workpiece is formed in the bonding stage. In a cutting stage, the clamp is displaceable away relative to the working zone to enable the laser to cut the sheet along a perimeter of the selective bonding.

WO 2024/177566 A1